TOSHIBA PHOTOCOUPLER

TLP665(D4)SERIES

ATTACHMENT: SPECIFICATIONS FOR VDE0884 OPTION: (D4)

Types: TLP665G, TLP665J, TLP665GF, TLP665JF, TLP666G, TLP666J, TLP666GF, TLP666JF

Type designations for 'Option: (D4)', which are tested under VDE0884 requirements.

Ex. : TLP665G (D4-T7) D4 : VDE0884 option

T7 : IFT rank name

Note : Use Toshiba standard type number for safety standard application.

Ex. TLP665G (D4-T7) \rightarrow TLP665G, TLP666JF (D4) \rightarrow TLP666JF

VDE0884 ISOLATION CHARACTERISTICS

DESCRIPTION	SYMBOL	RATING	UNIT
Application Classification			
(DIN VDE0109 / 12.83, Table 1)			
for rated mains voltage \leq 300 $ m V_{rms}$		I-IV	_
for rated mains voltage \leq 600 $ m V_{rms}$		I-III	
Climatic Classification		FF / 100 / 01	
(DIN IEC68 Teil 1/09.80)		55/100/21	_
Pollution Degree (DIN VDE0109/12.83)		2	_
Maximum Operating Insulation Voltage	V _{IORM}	630	Vpk
Input to output Test Voltage, Method A			
Vpr=1.2×V _{IORM} , Type and Sample Test	Vpr	760	Vpk
tp=60s, Partial Discharge<5pC			
Input to output Test Voltage, Method B			
Vpr=1.6×V _{IORM} , 100% Production Test	Vpr	1000	Vpk
tp=1s, Partial Discharge<5pC			
Highest Permissible Overvoltage	77	6000	Vpk
(Transient Overvoltage, t _{pr} =10s)	$V_{ m TR}$		
Safety Limiting Values (Max. permissible ratings in			
case of fault, also refer to thermal derating curve)			
Current (Input current I _F , P _{Si} =0)	I_{si}	400	mA
Power (Output or Total Power Dissipation)	P_{si}	700	mW
Temperature	T_{si}	150	°C
Insulation Resistance at T _{Si} , V _{IO} =500V	R _{si}	\geq 10^{9}	Ω

INSULATION RELATED SPECIFICATIONS

		7.62mm pitch TLPxxx type	10.16mm pitch TLPxxxF type	
Minimum Creepage Distance (*)	Cr	7.0mm	8.0mm	
Minimum Clearance (*)	Cl	7.0mm	8.0mm	
Minimum Insulation Thickness	ti	0.5mm		
Comperative Tracking Index	CTI 175		CTI	75
(DIN IEC112/VDE0303, Part 1)		(VDE0109/12.83 Group I I a)		

- ((*) in accordance with DIN VDE0109/12.83, Table 2, & 4)
 - (*1) If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value (e. g. at a standard distance between soldering eye centres of 7.5mm). If this is not permissible, the user shall take suitable measures.
 - (*2) This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data.

Maintenance of the safety data shall be ensured by means of protective circuits.

VDE Test sign: Marking on product

for VDE0884



Marking on packing for VDE0884



0884

2 2001-06-01

Figure 1 Partial discharge measurement procedure according to VDE0884 Destructive test for qualification and sampling tests.

Method A

(for type and sampling tests, destructive tests)

$$\begin{array}{lll} t_1, \ t_2 & = 1 \ to \ 10s \\ t_3, \ t_4 & = 1s \\ t_P \ (\text{Measuring time for} \\ & \text{partial discharge}) & = 50s \\ t_b & = 62s \\ t_{\text{ini}} & = 10s \end{array}$$

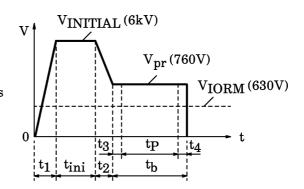
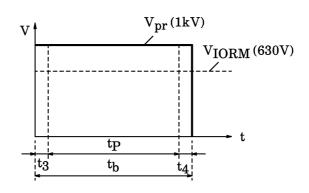


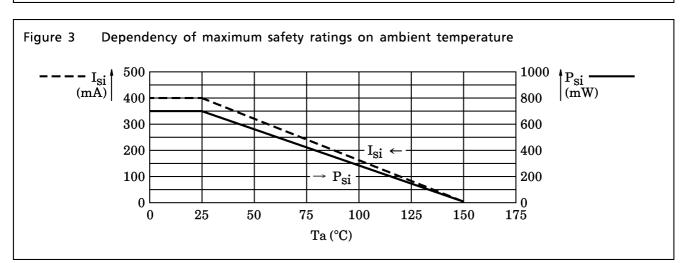
Figure 2 Partial discharge measurement procedure according to VDE0884 Non-destructive test for 100% inspection.

Method B

(for sample test, non-destructive test)

$$\begin{array}{ll} t_3,\ t_4 & = 0.1s \\ t_P \ (\text{Measuring time for} \\ & \text{partial discharge}) \ = 1s \\ t_b & = 1.2s \end{array}$$





3 2001-06-01

RESTRICTIONS ON PRODUCT USE

000707EBC

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